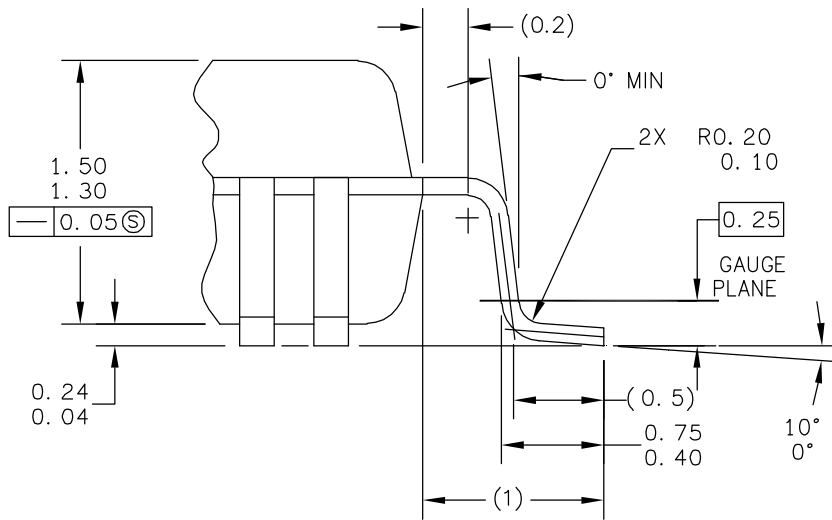
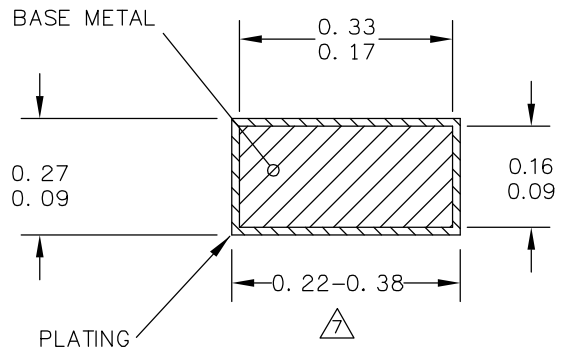
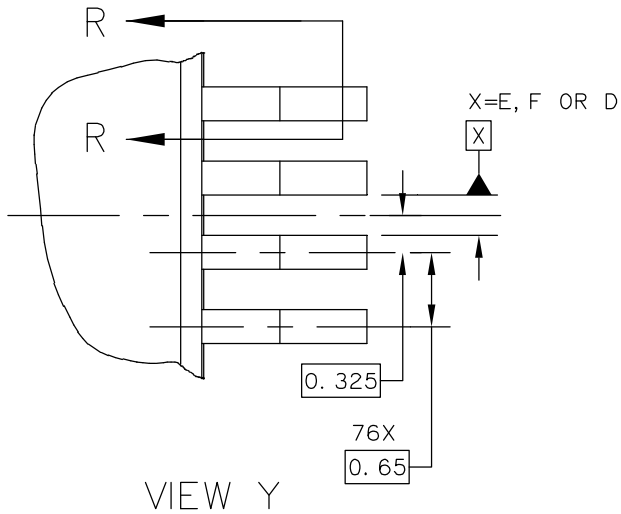


© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE
TITLE: 80 LD LQFP, 14 X 14 PKG, 0.65 MM PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23237W	REV: F
	STANDARD: NON-JEDEC	
	SOT823-3	26 JAN 2016



© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: 80 LD LQFP, 14 X 14 PKG, 0.65 MM PITCH, 1.4 THICK		DOCUMENT NO: 98ASS23237W	REV: F
		STANDARD: NON-JEDEC	
		SOT823-3	26 JAN 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION : MILIMETER.
3. DATUM PLANE H IS LOCATED AT THE BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUM E, F AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: 80 LD LQFP, 14 X 14 PKG, 0.65 MM PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23237W		REV: F
	STANDARD: NON-JEDEC		
	SOT823-3	26 JAN 2016	